

/ Descriptions

TO-263

Schottky Barrier Diode in a TO-263 Plastic Package.

/ Features

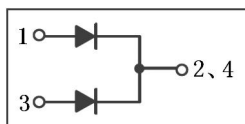
Low forward voltage drop, low power losses, High efficiency operation.

/ Applications

OR-ing

DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode

PIN 2 4 Cathode

PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings($T_a=25$)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	45	V
Average forward rectified Current	I_F	2X15	A
Non Repetitive Peak Surge Current	I_{FSM}	250	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40~+150	

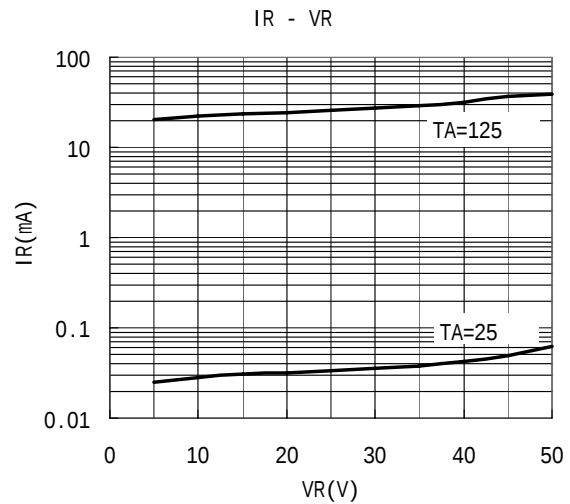
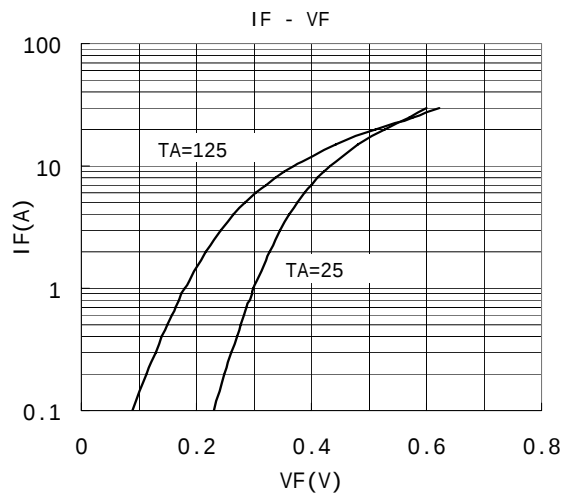
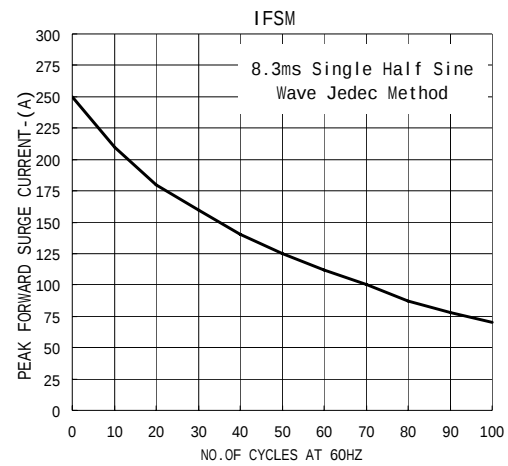
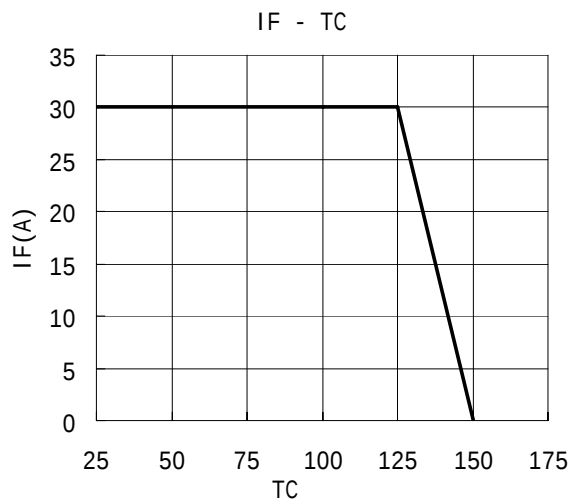
/ Electrical Characteristics($T_a=25$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA$ $T_a=25$	45			V
Forward Voltage	V_{FM}	$I_F=5.0A$ $T_a=25$		0.38	0.45	V
		$I_F=15A$ $T_a=25$		0.48	0.55	V
		$I_F=5A$ $T_a=125$		0.28	0.35	V
		$I_F=15A$ $T_a=125$		0.45	0.50	V
Instantaneous Reverse Current	I_R Note 1	$V_R=45V$ $T_a=25$			200	μA
		$V_R=45V$ $T_a=125$		40	100	mA

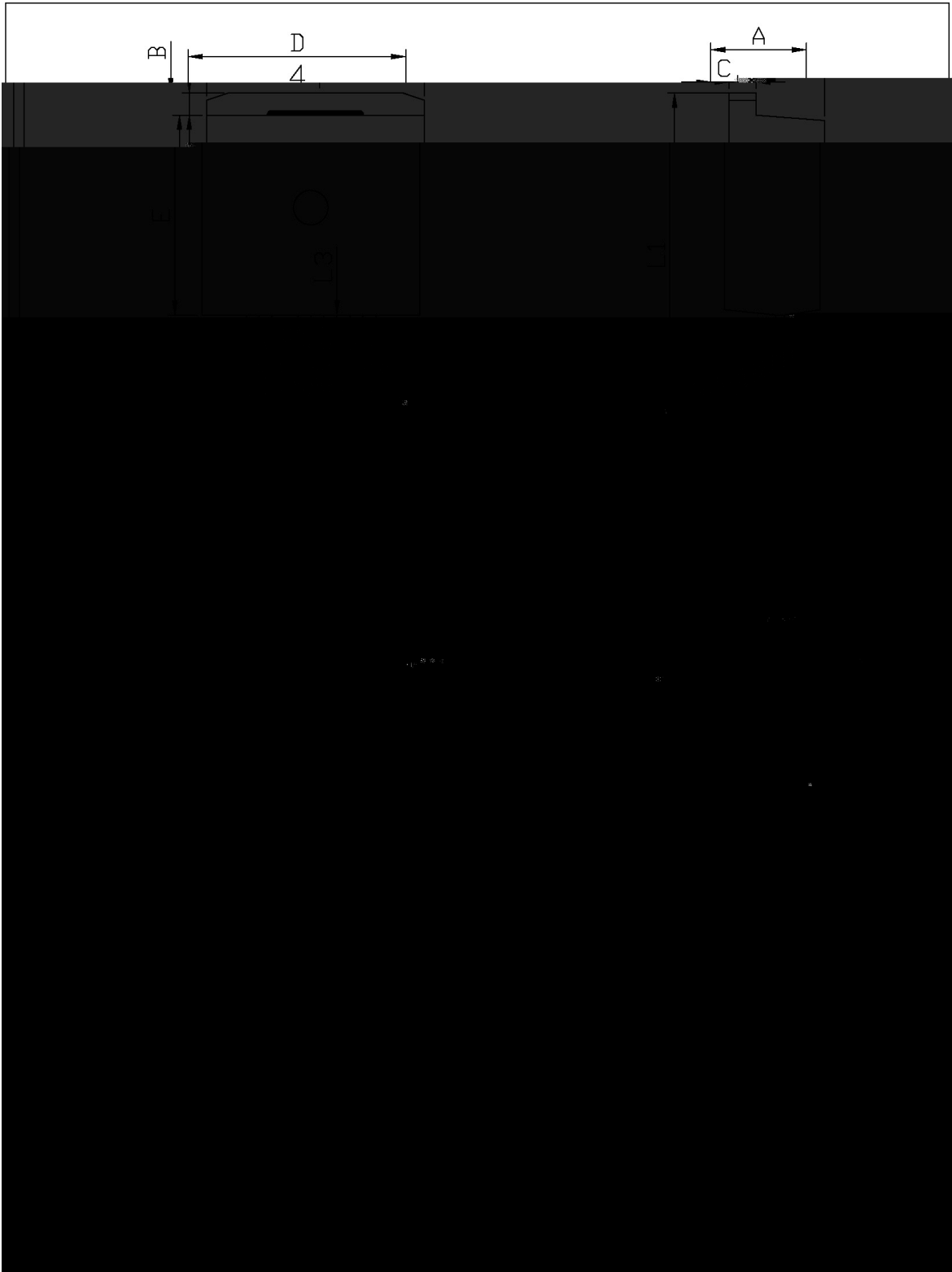
/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip.

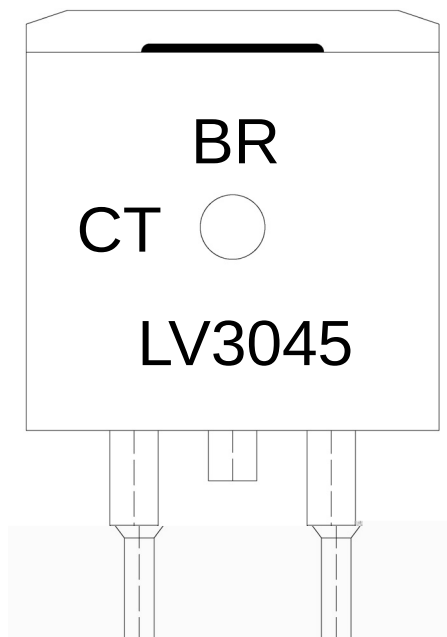
I Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

LV3045

CT:

Note:

BR:

Company Code

LV3045

Product Type.

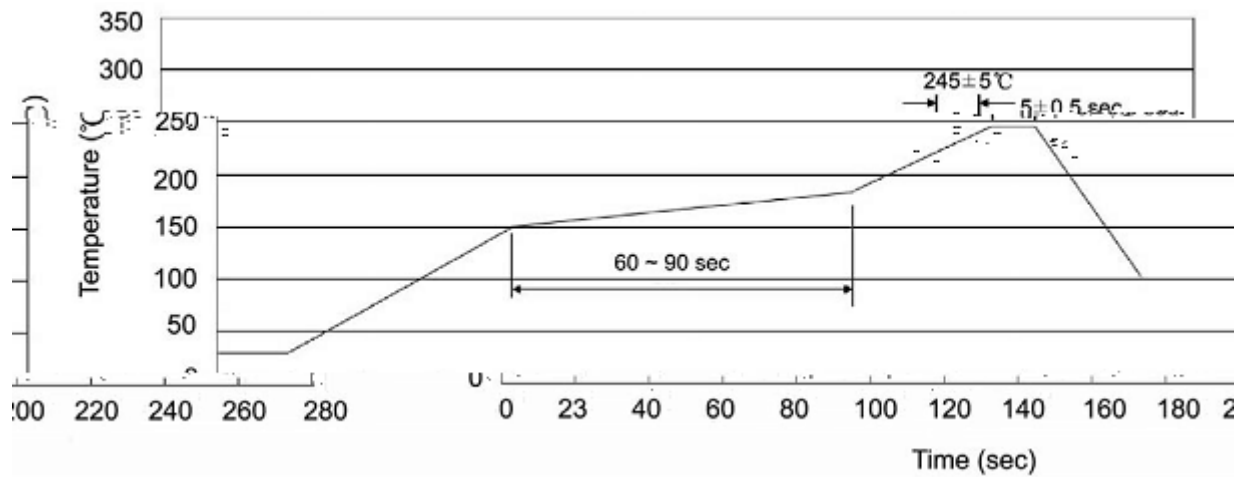
CT:

Internal Structure

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱	p> ()Tj 45J /TT7 1 2 302 TD451.22.52 240.54 0.480011